L .	Hits	Search Text	DB	Time stamp
Number	000	1100 - 1 - 10	HODAT	2004/07/12
1	232	modul\$3 and multi near layers and mount\$3	USPAT; US-PGPUB;	
		near pad\$1	1	08:59
			EPO; JPO; DERWENT;	
			IBM_TDB	•
2	24	29/830.ccls. and multi adj layer and pcb and	USPAT;	2004/07/12
_	2-	pads and connections	US-PGPUB;	08:54
		paus and connections	EPO; JPO;	00.34
			DERWENT;	
			IBM_TDB	
3	38	multi adj layer and pcb and pads and edge	USPAT;	2004/07/12
		near connections	US-PGPUB;	08:56
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
4	3	modul\$3 near one and two and pad\$1 and	USPAT;	2004/07/12
		edge near joint	US-PGPUB;	09:00
		<u> </u>	EPO; JPO;	,
			DERWENT;	
			IBM_TDB	
5	2	modul\$3 near edge near joint	USPAT;	2004/07/12
			US-PGPUB;	09:01
			EPO; JPO;	
		·	DERWENT;	
			IBM_TDB	
6	11665	pcb and pcb and pads	USPAT;	2004/07/12
			US-PGPUB;	09:03
		·	EPO; JPO;	
			DERWENT;	
			IBM_TDB	
7	195	multilayer near pcb and pads	USPAT;	2004/07/12
			US-PGPUB;	09:15
			EPO; JPO;	
		·	DERWENT;	
_			IBM_TDB	
8	12	multilayer near pcb and edge near	USPAT;	2004/07/12
		connection	US-PGPUB;	09:16
		·	EPO; JPO;	
			DERWENT;	
0	_	20040060007 HPPN	IBM_TDB	2004/07/42
9	0	20040069997.URPN.	USPAT	2004/07/12
40	371	multilever near neb and connection	HEDAT:	09:16
10	3/1	multilayer near pcb and connection	USPAT;	2004/07/12
			US-PGPUB;	09:17
			EPO; JPO; DERWENT;	
		·	IBM_TDB	
11	5524	pcb and interconnection	USPAT;	2004/07/12
••	3324	pou ana interconnection	US-PGPUB;	09:17
			EPO; JPO;	V3.17
			DERWENT;	
			IBM_TDB	

12	329	pcb and interconnection and 29/\$.ccls.	USPAT;	2004/07/12
	•	•	US-PGPUB;	09:23
			EPO; JPO;	
			DERWENT;	
0		•	IBM_TDB	
13	13	("4793814" "5239198" "5309324"	USPAT	2004/07/12
		"5321583" "5475261" "5490040"		09:20
		"5758099" "5796169" "5923083"		
		"6053394" "6097609" "6219241"		
		"6463493" "2002/0065965").PN.		
14	24	("2936439" "3217283" "3217284"	USPAT	2004/07/12
		"3569789" "3795037" "3904934"		09:22
1		"3934959" "3980375" "3992761"		
		"4003621" "4008300" "4082399"		
1		"4150420" "4161346" "4199209"		
		"4249787" "4295700" "4330165"		
		"4367908" "4402562" "4408814"		
		"4445735" "4509099" "4593961").PN.		
15	473	pcb and interconnection and (174/260,	USPAT;	2004/07/12
		174/267, 257/690, 257/696, 257/786,	US-PGPUB:	09:24
,	•	29/832	EPO; JPO;	
		, 29/840 , 29/854 , 361/772 ,	DERWENT;	
i		361/773 , 438/106 , 438/108).ccls.	IBM_TDB	
16	95	pcb and interconnection and (174/260,	USPAT;	2004/07/12
		174/267, 257/690, 257/696, 257/786,	US-PGPUB;	09:29
		29/832	EPO; JPO;	000
		, 29/840 , 29/854 , 361/772 ,	DERWENT;	
		361/773 , 438/106 , 438/108).ccls. and	IBM_TDB	
		multilayer		
17	329	Cheng near Yu .inv.	USPAT;	2004/07/12
			US-PGPUB:	09:30
			EPO; JPO;	
			DERWENT;	
	·		IBM_TDB	
18	5	Cheng near Yu .inv. and pcb	USPAT;	2004/07/12
		, , , , , , , , , , , , , , , , , , ,	US-PGPUB;	09:31
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
19	5	Cheng near chiang .inv. and pcb	USPAT;	2004/07/12
		onong nour onlang more and pos	US-PGPUB;	09:32
			EPO; JPO;	00.02
			DERWENT;	
			IBM_TDB	
20	. 12	Cheng adj yu near chiang .inv.	USPAT;	2004/07/12
	• •-	eneng aaj ya near emang mivi	US-PGPUB;	09:33
			EPO; JPO;	05.50
			DERWENT;	
		•	IBM_TDB	
21	6	"multilayer pcb assembly"	USPAT;	2004/07/12
	3		US-PGPUB;	09:34
			EPO; JPO;	U3:34
			DERWENT;	,
		•	PERTERI	i

22	23	"multilayer pcb" and 29/\$.ccls.	USPAT;	2004/07/12
			US-PGPUB;	09:37
			EPO; JPO;	
			DERWENT;	· .
•			IBM_TDB	
23	5	("3673680" "4304640" "4487654"	USPAT	2004/07/12
		"4525246" "5024734").PN.		09:36
24	1555	"multilayer assembly" PCB and 29/\$.ccls.	USPAT;	2004/07/12
			US-PGPUB;	09:37
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
25	2	"multilayer assembly" and PCB and	USPAT;	2004/07/12
		29/\$.ccls.	US-PGPUB;	09:45
			EPO; JPO;	
		·	DERWENT;	
00	2005		IBM_TDB	2004/07/40
26	2005	multilayer and (pcb or pwb or substrate) and	USPAT;	2004/07/12
		29/\$.ccls.	US-PGPUB;	09:47
			EPO; JPO;	
			DERWENT;	
27	434	multilayer and (pcb or pwb or substrate) and	IBM_TDB USPAT;	2004/07/12
21	434	29/\$.ccls. and modules	US-PGPUB;	09:47
		29/3.ccis. and modules	EPO; JPO;	05:47
			DERWENT;	,
			IBM_TDB	
28	44	multilayer and (pcb or pwb or substrate) and	USPAT;	2004/07/12
		29/\$.ccls. and modules and solder near pads	US-PGPUB;	10:22
•			EPO; JPO;	
			DERWENT;	
	1 .		IBM_TDB	
29	6	("5581876" "5801073" "5821617"	USPAT	2004/07/12
		"5847935" "5940271" "6008991").PN.		09:53
30	11	multilayer near (pcb or pwb or substrate)	USPAT;	2004/07/12
		and 29/\$.ccls. and modules and solder near	US-PGPUB;	10:23
		pads .	EPO; JPO;	
		•	DERWENT;	
		•	IBM_TDB	
31	7707	multilayer near (pcb or pwb or substrate)	USPAT;	2004/07/12
		andcircuit near traces and pad\$1	US-PGPUB;	10:24
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
32	71	multilayer near (pcb or pwb or substrate)	USPAT;	2004/07/12
		and circuit near traces and pad\$1	US-PGPUB;	10:33
			EPO; JPO;	
			DERWENT;	
33	4470	madula and almost mass to see and as the	IBM_TDB	2004/07/42
33	1172	module and circuit near traces and pad\$1	USPAT;	2004/07/12
			US-PGPUB;	10:34
			EPO; JPO;	
			DERWENT; IBM_TDB	

34	91	module near assembly and circuit near traces and pad\$1	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/12 10:45
35	8	("5069641" "5587884" "5647767" "5687233" "6010367" "6227911" "6302741" "6319064").PN.	USPAT	2004/07/12 10:36
36	10	("4772224" "5015204" "5069641" "5139442" "5282759" "5531612" "5587884" "5687233" "5816830" "6019631").PN.	USPAT	2004/07/12 10:37
37		("3460010" "3538397" "3769105" "3772097" "4164751" "4266282" "4317686" "4349862" "4423431" "4427989" "4477736" "4493056" "4567542" "4577214" "4604639" "4605980" "4641425" "4649418" "4654690" "4656605" "4691304" "4720737" "4725924" "4731645" "4737830" "4748495" "4777518" "4780846" "4835416" "4931853" "4937649" "4991000" "4992849" "4992850" "4996587" "5012323" "5016138" "5032892" "5045921" "5107328" "5128831" "5137836" "5182632" "5239198" "5255156" "5266821" "5280192" "5280193" "5307309" "5322207" "5323060" "5367435" "5399898" "5422435" "5434745" "5437082" "5480840" "5483024" "5495398" "5502289"	USPAT	2004/07/12 10:40
38	14	"5535101" "6013948" "6054753").PN. ("4288841" "4398235" "4551746" "4884237" "4956694" "4983533" "4996587" "5019943" "5036431" "5043794" "5128831" "5165067" "5222014" "5247423").PN.	USPAT	2004/07/12 10:42
39	12	chip near module and stacking and circuit near traces and pad\$1 and (257/706; 257/707; 257/723; 257/724; 174/252; 174/261; 174/254; 165/80.3; 165/185; 439/485; 439/66-69 ; 361/386; 361/396; 361/398; 361/403; 361/405 ; 361/409; 361/410; 361/412; 361/413; 361/421; 361/411).ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/12 10:48

40	145	module and stacking and circuit near	USPAT;	2004/07/12
1		traces and pad\$1	US-PGPUB;	11:25
		PK I	EPO; JPO;	
			DERWENT;	
			IBM_TDB	
41	0	multilayer near pcb and stacking and	USPAT;	2004/07/12
		circuit near traces and 29/\$.ccls.	US-PGPUB;	11:26
1			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
42	4	pcb and stacking and circuit near traces	USPAT;	2004/07/12
		and 29/\$.ccls.	US-PGPUB;	11:26
İ			EPO; JPO;	
		•	DERWENT;	:
			IBM_TDB	
43	10	("3646670" "3832769" "3835531"	USPAT	2004/07/12
		"4648179" "5046238" "5282312"		11:28
		"5309629" "5401913" "5440075"		
	•	"5502884").PN.		
44	33	("3077511" "3214827" "3316618"	USPAT	2004/07/12
		"3509270" "3541222" "3546775"		11:36
-		"3606677" "3616532" "3739469"	•	
	•	"3775844" "3795037" "3795047"		
		"3829601" "3859711" "3862790"	<i>'</i> .	·
	•	"4024629" "4211603" "4216350"		
		"4249302" "4383363" "4642889"		
		"4712161" "4729809" "4788766"		·
·		"4793814" "4935584" "4954878"		
		"5046238" "5069628" "5072075"		
		"5089880" "5129142" "5140745").PN.		
45	67	5282312.URPN.	USPAT	2004/07/12
	-		~	11:40